



ULTRA-DENSE MULTI-ROW STRIP

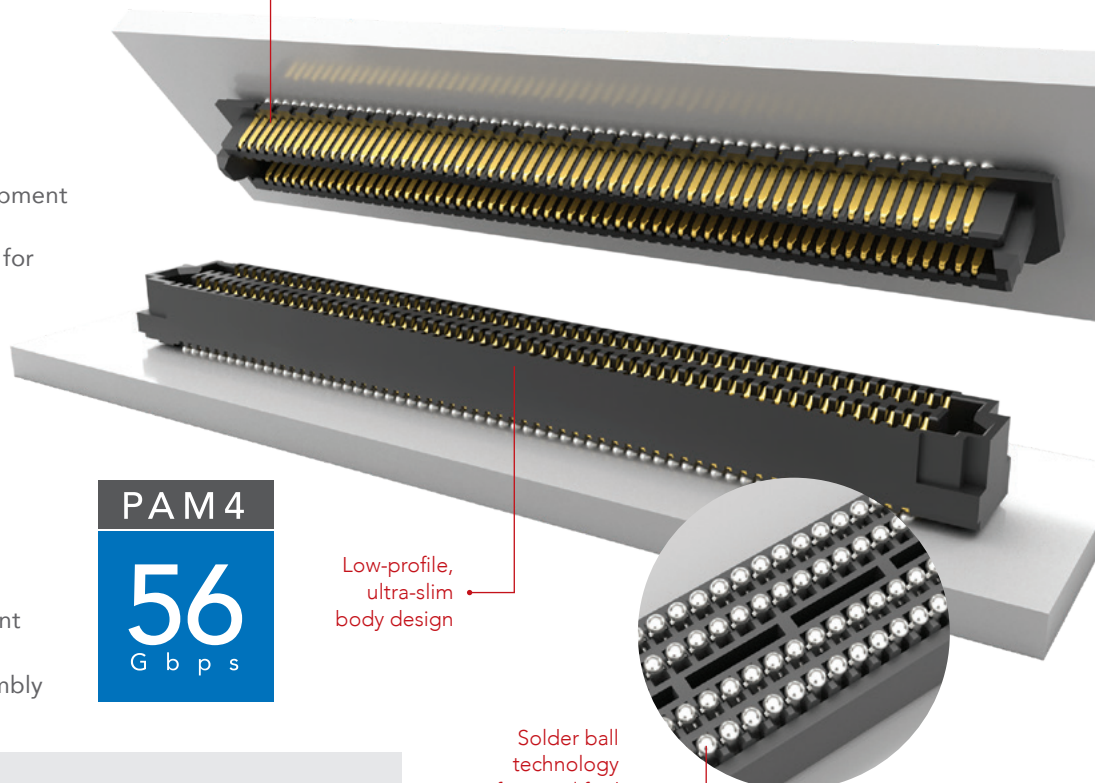
0.635 mm PITCH ACCELERATE[®] HD MICRO INTERCONNECTS

Features & Benefits

- Low-profile 5 mm stack height
- Slim 5 mm width
- Incredibly dense - up to 240 total I/Os
 - 4-row design
 - 10 - 60 positions per row
 - 70 - 100 positions per row in development
- Edge Rate[®] contact system optimized for signal integrity performance
- Open-pin-field design for grounding and routing flexibility
- Supports 56 Gbps PAM4 (28 Gbps NRZ) applications
- PCIe[®] Gen 5 compatible
- 7 - 16 mm stack heights in development
- Roadmap: right-angle and cable assembly

0.635 mm pitch

ACCELERATE[®] HD

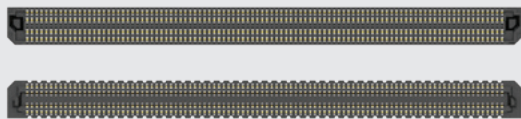


PAM4
56
Gbps

Low-profile, ultra-slim body design

Solder ball technology for simplified processing

ACTUAL SIZE



68.22 mm x 5.00 mm

ADM6/ADF6 Series (400 total positions)

SYSTEM

- ADM6 Series – 0.635 mm Pitch Micro Header
- ADF6 Series – 0.635 mm Pitch Micro Socket

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Please visit samtec.com/acceleratehd for additional information about AcceleRate[®] HD.